

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

QFN 5mm X 6mm Exp.Pad

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**TOTAL MASS (g) : 0.073268**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005041	1000000	68802.0625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.025794	975000	352049.28125		
		Iron (Fe)	7439-89-6	0.000635	24000	8666.79492188		
		Phosphorus (P)	7723-14-0	0.000008	299.999908447	109.187965393		
		Zinc (Zn)	7440-66-6	0.000019	700	259.321411133		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.026456</b>	<b>1000000</b>	<b>361084.625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001276	1000000	17417.5507812		
		<b>External Plating Total:</b>				<b>0.001276</b>	<b>1000000</b>	<b>17417.5507812</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000573	1000000	7820.58837891		
<b>Internal Plating Total:</b>				<b>0.000573</b>	<b>1000000</b>	<b>7820.58837891</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001758	750000	23994.0566406		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000586	250000	7998.01855469		
<b>Die Attach Total:</b>				<b>0.002344</b>	<b>1000000</b>	<b>31992.0742188</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004876	130000	66550.0703125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.032257	860000	440259.5625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000375	10000	5118.18603516		
		<b>Encapsulation Total:</b>				<b>0.037508</b>	<b>1000000</b>	<b>511927.78125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000070	1000000	955.394775391		
					<b>TOTAL MASS (g) :</b>	<b>0.073268</b>		